

SAW Components

For Band1/Unbalanced/5pin/1109



Series type: QGSA2G14AASP2

Ordering code: QGSA2G14AASP2

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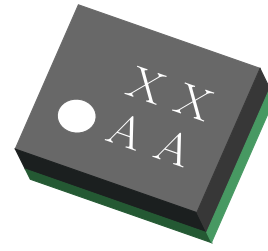
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Contents

1 Applications	3
2 Features	3
3 Package	4
4 Pin configuration	4
5 Matching circuit	5
6 Absolute Maximum Ratings	5
7 Characteristics	6
8 Transmission coefficients	7
9 Soldering profile	8
10 Tape and Reel	9
10.1 Tape	9
10.2 Reel with diameter of 178 mm	9

1 Applications

- Saw filter for Cellular/Cordless phone(Terminal) relevant market

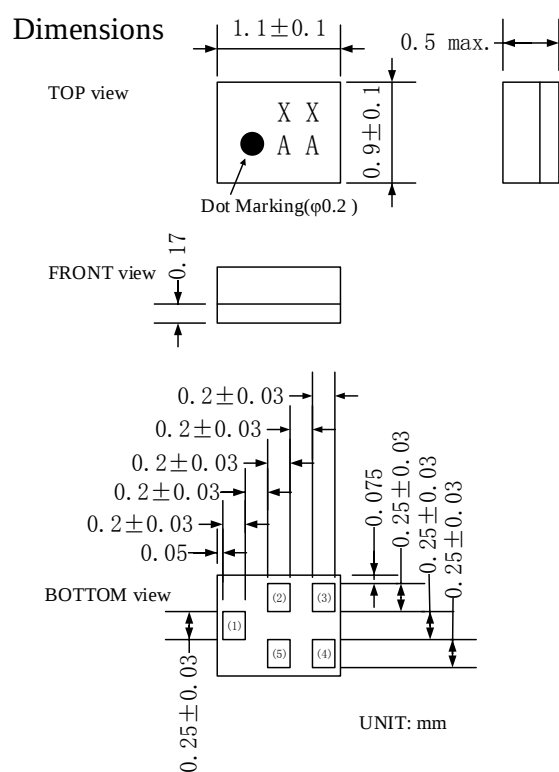


2 Features

- Package size 1.1 mm x 0.9 mm
- Package height 0.5 mm (max.)
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

Figure 1: Picture of component with example of product marking.

3 Package



Land Pattern

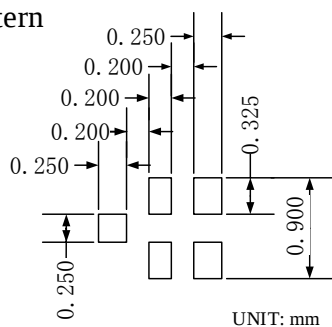


Figure 2: Drawing of package with package height $A = 0.5$ mm (max.)

4 Pin configuration

- 1 Unbalance Port
- 4 Unbalance Port
- 2,3,5 Ground

5 Matching circuit

- $R_1 : 50\Omega$ $R_2 : 50\Omega$

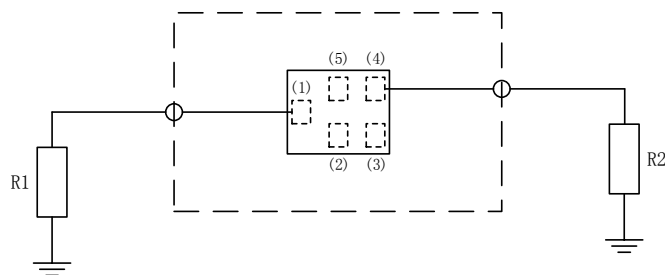


Figure 3: Schematic of matching circuit.

6 Absolute Maximum Ratings

Table 1: Absolute Maximum Ratings of Example Data Sheet

Parameter	Rating
Storage temperature	$T_{STG} = -40^{\circ}C$ to $+85^{\circ}C$
Operating temperature	$T_{opt} = -30^{\circ}C$ to $+85^{\circ}C$
DC voltage	$V_{DC} = 3.0V(max)$
Input power	$P_{IN} = +10dBm$ 5000h
Minimum Resistance between the terminals	10Mohm

7 Characteristics

Temperature range for specification $T_{SPEC} = -30^{\circ}C \dots +85^{\circ}C$

Input terminating impedance $Z_{IN} = 50\Omega$

Output terminating impedance $Z_{OUT} = 50\Omega$

Item		min.	typ.	max.	Unit	Note
Center Frequency		2140			MHz	
Insertion Loss	2110 to 2170 MHz		1.7	2.8	dB	
Ripple Deviation	2110 to 2170 MHz		0.7	1.2	dB	
VSWR	2110 to 2170 MHz		1.5	2.0		
Absolute Attenuation	450 to 1920 MHz	33	38		dB	
	699 to 716 MHz	40	45		dB	
	777 to 787 MHz	40	45		dB	
	814 to 849 MHz	40	44		dB	
	824 to 894 MHz	42	44		dB	
	880 to 915 MHz	40	45		dB	
	898 to 925 MHz	42	45		dB	
	1710 to 1755 MHz	40	46		dB	
	1730 to 1920 MHz	38	40		dB	
	1920 to 1980 MHz	41	46		dB	
	2015 to 2075 MHz	10	12		dB	
	2185 to 2300 MHz	2.0	2.6		dB	
	2300 to 2400 MHz	30	35		dB	
	2400 to 2500 MHz	36	38		dB	
	4030 to 4150 MHz	28	32		dB	
	4220 to 4340 MHz	27	30		dB	
	4900 to 5950 MHz	20	25		dB	

8 Transmission coefficients

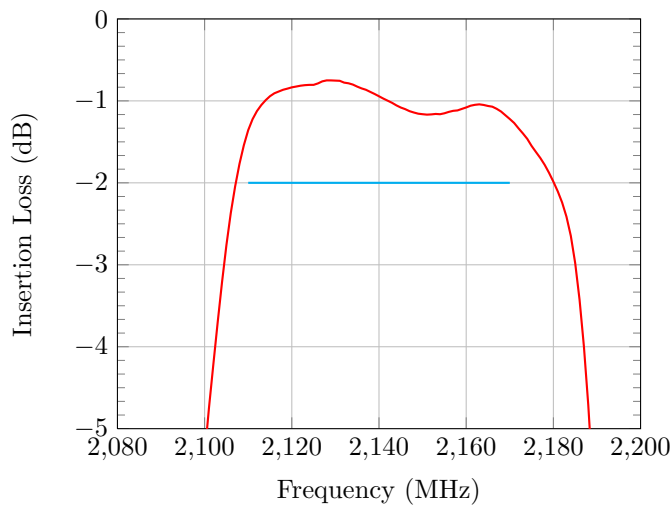


Figure 4: Passband

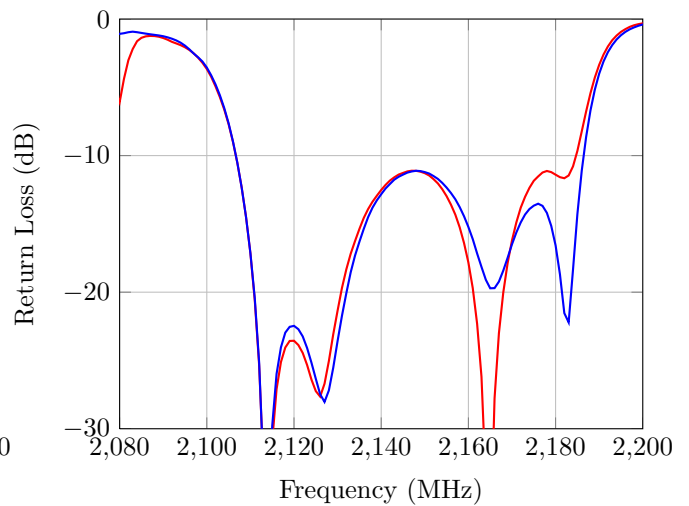


Figure 5: Input/Output Return Loss

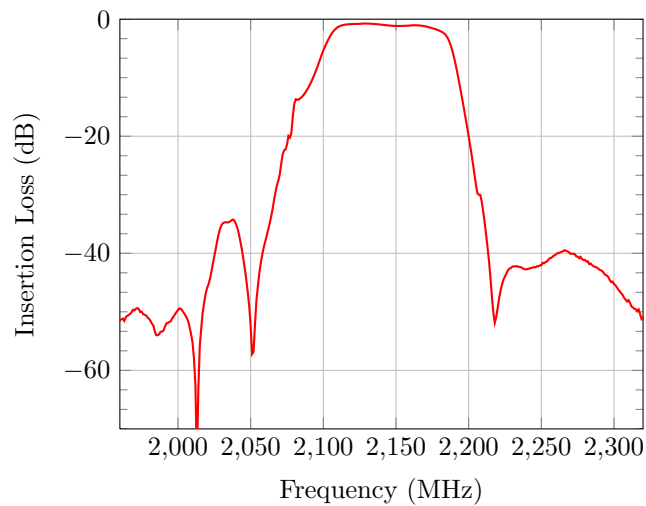


Figure 6: Narrowband

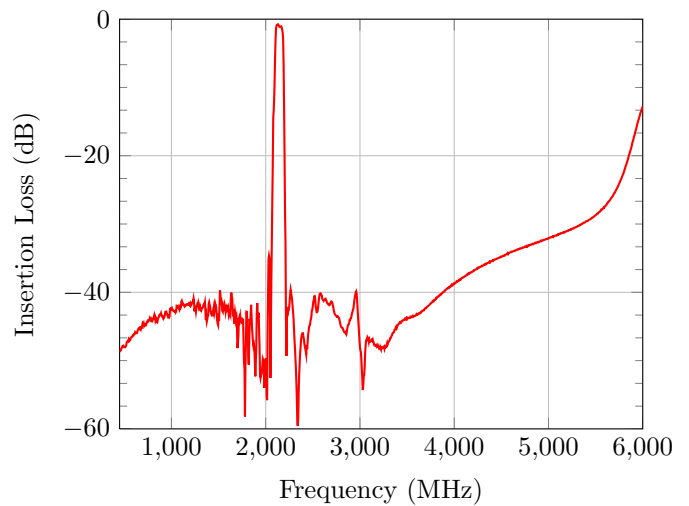
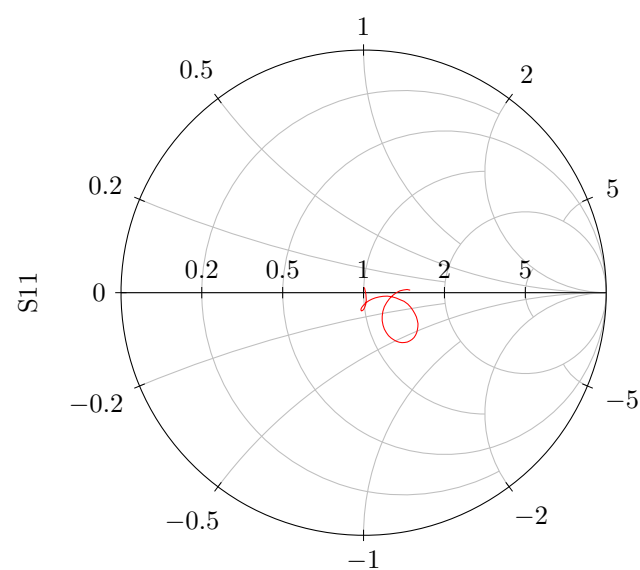
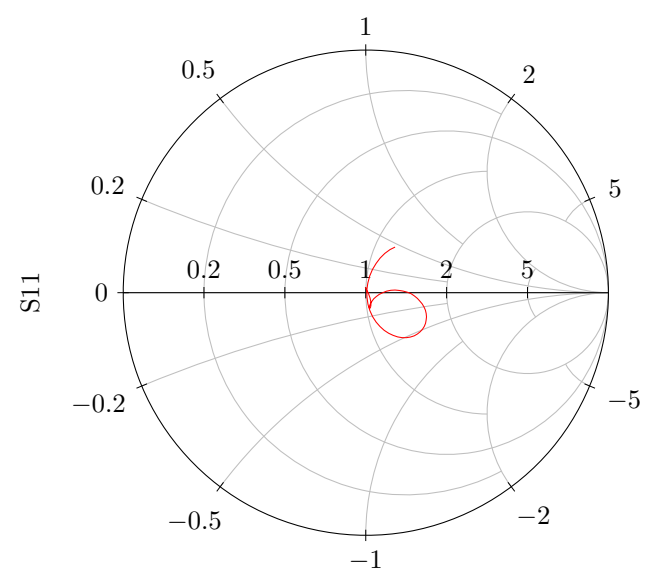


Figure 7: Wideband

Figure 8: Input Smith Chart ($Z_0 = 50\Omega$)Figure 9: Output Smith Chart ($Z_0 = 50\Omega$)

9 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58-3rd edit and IPC/JEDECJ-STD-020B.

Table 2: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

Parameter	Rating
Ramp rate	≥ 3 K/s
Preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T >220 °C	30 s to 70 s
T >230 °C	Min. 10 s
T >245 °C	Max. 20 s
T $\leq$ 255 °C	-
Peak temperature T_{peak}	220 °C $\pm$ 5°C
Wetting temperature T_{min}	230 °C $\pm$ 5°C for 10s $\pm$ 1s
Cooling rate	≥ 3 K/s
Soldering temperature T	Measured at solder pads

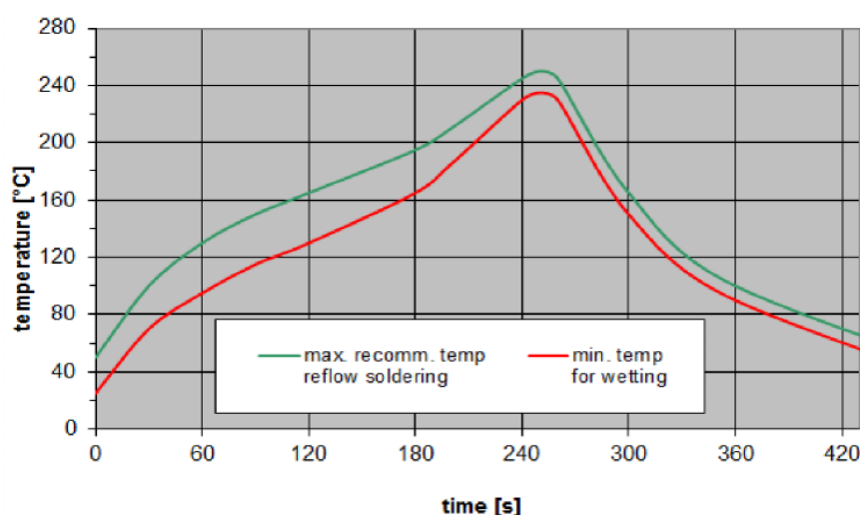


Figure 10: Drawing of reel (Recommended reflow profile for convection and infrared soldering – lead-free solder)

10 Tape and Reel

10.1 Tape

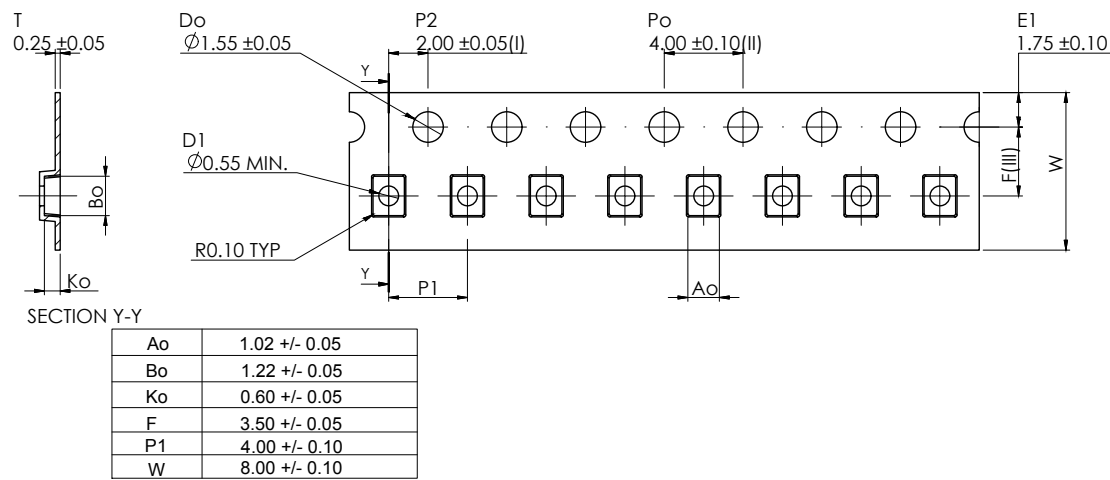


Figure 11: Drawing of tape (first-angle projection) with tape dimensions

10.2 Reel with diameter of 178 mm

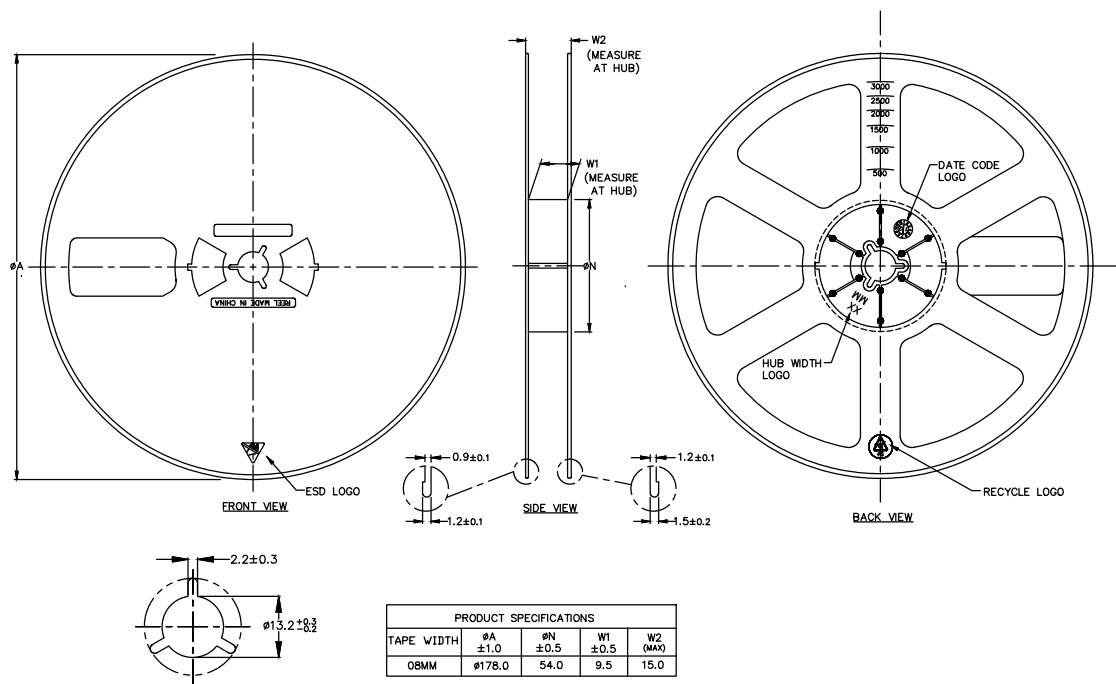


Figure 12: Drawing of reel (first-angle projection) with diameter of 180 mm